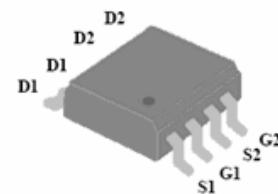
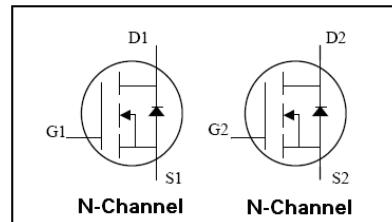


## Features

- ◆ 30V/8A
- ◆  $R_{on}(\text{typ.})=16\text{ m}\Omega$  @ $V_{GS}=10\text{ V}$
- ◆  $R_{on}(\text{typ.})=25\text{ m}\Omega$  @ $V_{GS}=4.5\text{ V}$
- ◆ Low On-Resistance
- ◆ 150°C Operating Temperature
- ◆ Fast Switching
- ◆ Lead-Free, Green Compliant

SOP8



## Description

VS3009DS designed by the trench processing techniques to achieve extremely low on-resistance. And fast switching speed and improved transfer effective . These features combine to make this design an extremely efficient and reliable device for variety of DC-DC applications.

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
<b>Common Ratings (<math>T_c=25^\circ\text{C}</math> Unless Otherwise Noted)</b>			
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	30	V
$T_J$	Maximum Junction Temperature	150	°C
$T_{STG}$	Storage Temperature Range	-50 to 150	°C
$I_s$	Diode Continuous Forward Current	$T_c=25^\circ\text{C}$	7.5 <sup>①</sup>

### Mounted on Large Heat Sink

$I_{DM}$	Pulse Drain Current Tested	$T_c=25^\circ\text{C}$	32 <sup>②</sup>	A
$I_D$	Continuous Drain Current( $V_{GS}=10\text{ V}$ )	$T_c=25^\circ\text{C}$	8 <sup>①</sup>	A
		$T_c=100^\circ\text{C}$	6.0	
$P_D$	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	3.1	W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient		48	°C/W
$R_{\theta JC}$	Thermal Resistance-Junction to Case		1.55	°C/W

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current ( $T_c=25^\circ\text{C}$ )	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	$\mu\text{A}$
	Zero Gate Voltage Drain Current ( $T_c=125^\circ\text{C}$ )	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.9	1.5	2.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=8\text{A}$	--	16	20	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=4.5\text{A}$	--	25	40	$\text{m}\Omega$
<b>Dynamic Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	450	--	pF
$C_{\text{oss}}$	Output Capacitance		--	69	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	40	--	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=20\text{V}, I_{\text{D}}=6\text{A}, V_{\text{GS}}=10\text{V}$	--	13	--	nC
$Q_{\text{gs}}$	GateSource Charge		--	3.6	--	nC
$Q_{\text{gd}}$	GateDrain Charge		--	5.0	--	nC
<b>Switching Characteristics</b>						
$t_{\text{d(on)}}$	Turnon Delay Time	$V_{\text{DD}}=20\text{V}, I_{\text{D}}=6\text{A}, R_{\text{G}}=3.3\Omega, V_{\text{GS}}=10\text{V}$	--	15	--	nS
$t_r$	Turnon Rise Time		--	19	--	nS
$t_{\text{d(off)}}$	TurnOff Delay Time		-	30	--	nS
$t_f$	TurnOff Fall Time		--	13	--	nS
<b>Source Drain Diode Characteristics</b>						
$I_{\text{SD}}$	Sourcedrain current(Body Diode)	$T_c=25^\circ\text{C}$	7.5 <sup>①</sup>	--	--	A
$V_{\text{SD}}$	Forward on voltage	$T_j=25^\circ\text{C}, I_{\text{SD}}=6\text{A}, V_{\text{GS}}=0\text{V}$	--	0.88	1.3	V

Notes:

① Pulse test ; Pulse width $\leq 300\mu\text{s}$ , duty cycle $\leq 2\%$ .

② Pulse width limited by maximum allowable junction temperature

### Typical Characteristics

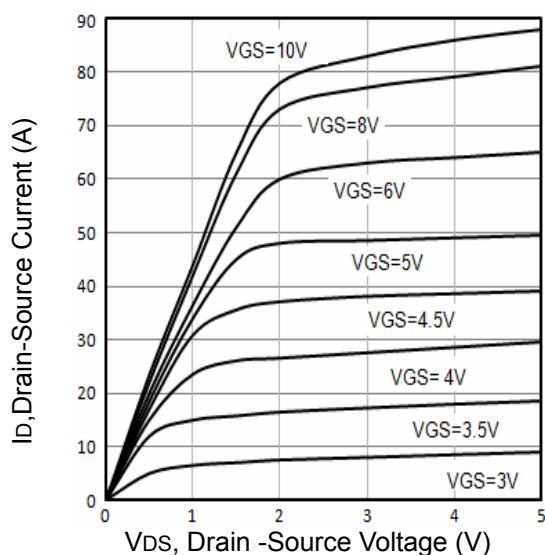


Fig1. Typical Output Characteristics

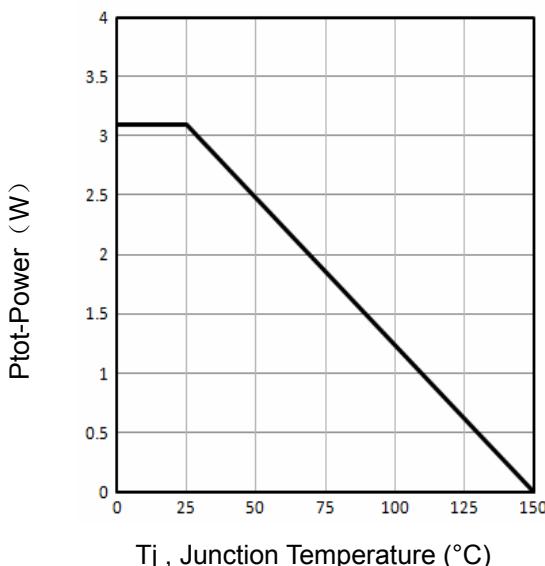


Fig2. Power Dissipation

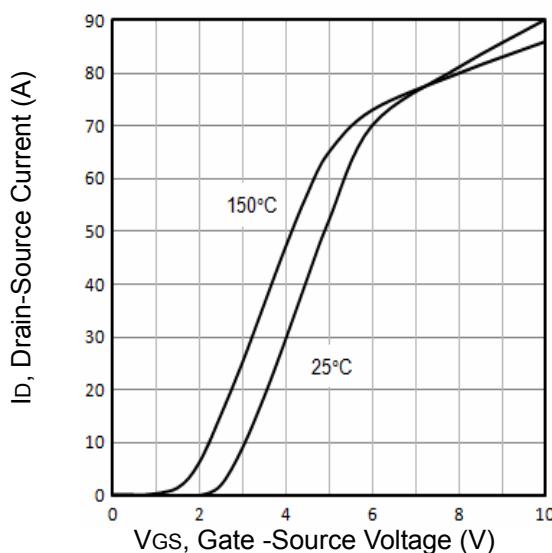


Fig3. Typical Transfer Characteristics

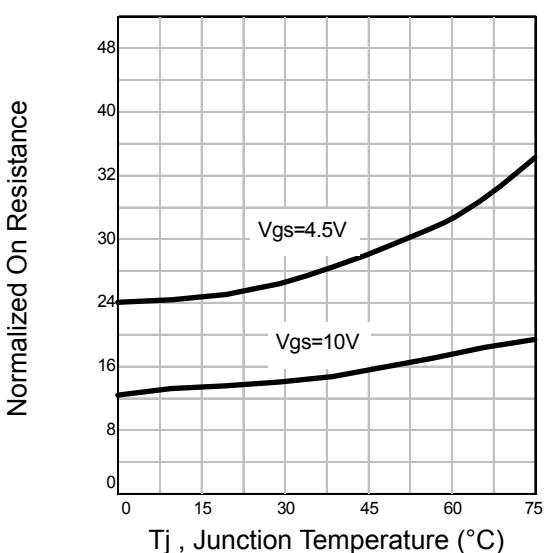


Fig4. Normalized On-Resistance Vs. Temperature

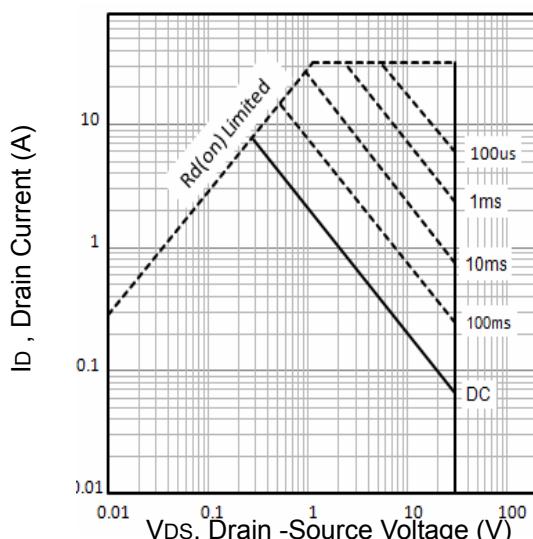


Fig5. Maximum Safe Operating Area

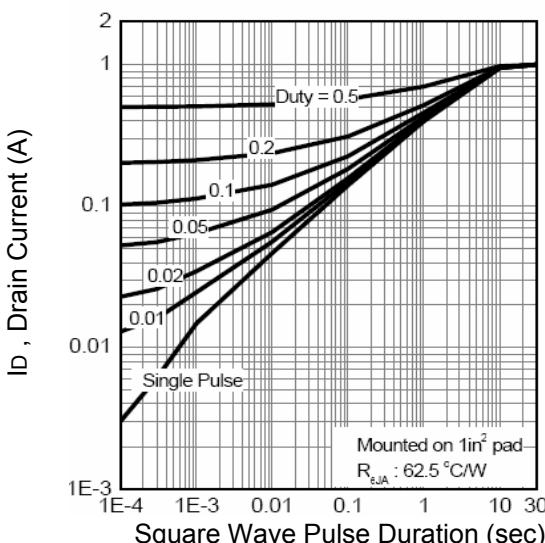


Fig6. Thermal Transient Impedance

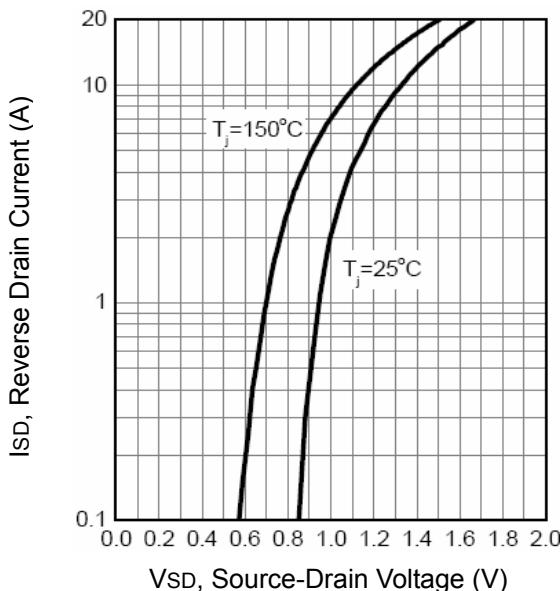


Fig7. Typical Source-Drain Diode Forward Voltage

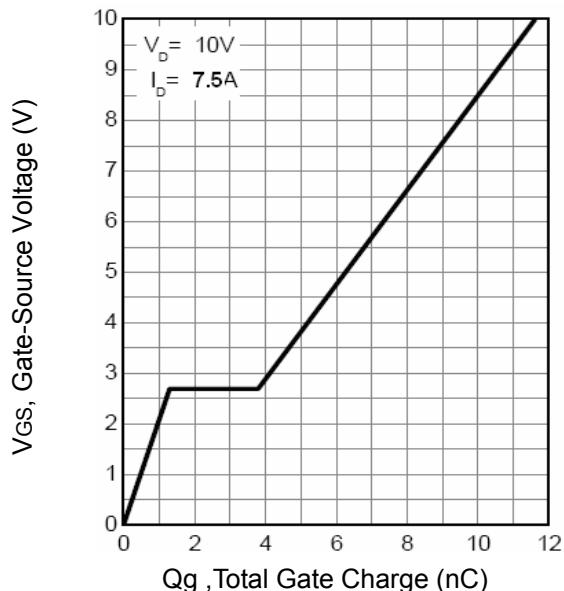


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

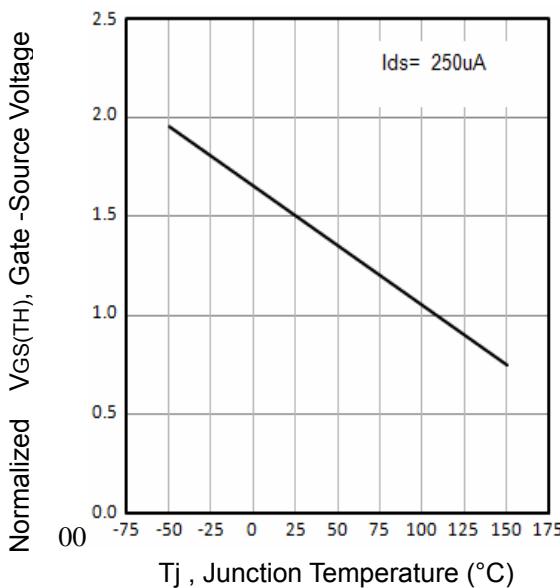


Fig9. Threshold Voltage Vs. Temperature

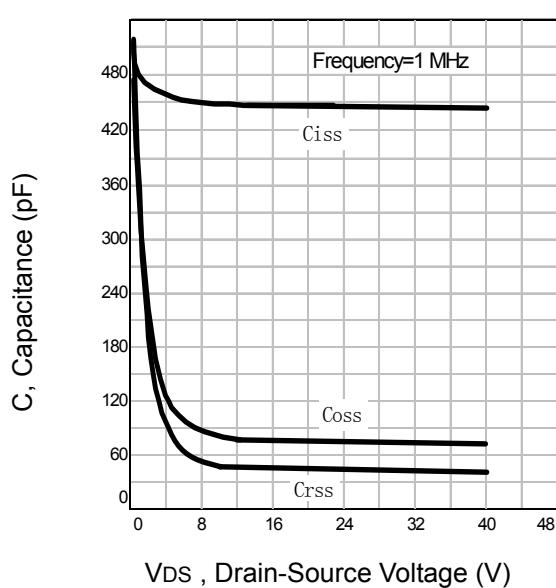


Fig10. Typical Capacitance Vs.Drain-Source Voltage

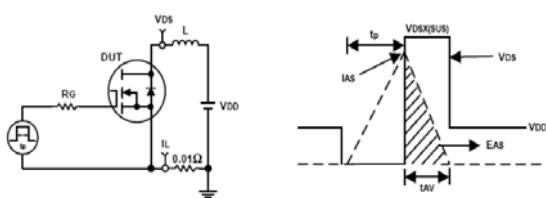


Fig11. Unclamped Inductive Test Circuit and waveforms

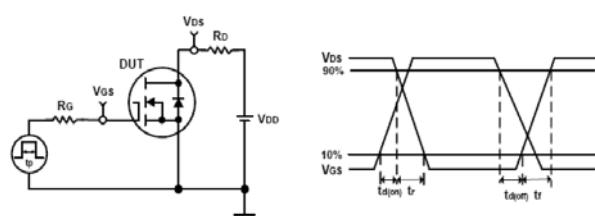
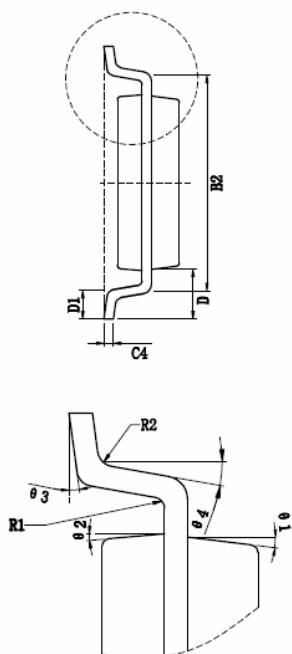
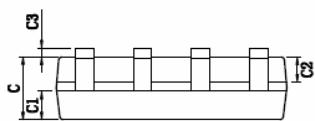
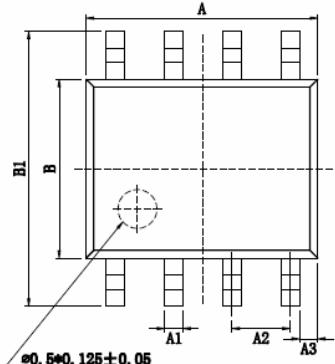


Fig12. Switching Time Test Circuit and waveforms

## SOP8 Mechanical Data



Symbol	Dimensions In Millimeters		
	Min	Nom	Max
A	4.800	4.900	5.000
A1	0.356	0.406	0.456
A2		1.270Typ.	
A3		0.345Typ.	
B	3.800	3.900	4.000
B1	5.800	6.000	6.200
B2		5.00Typ.	
C	1.300	1.400	1.500
C1	0.550	0.600	0.650
C2	0.550	0.600	0.650
C3	0.050	--	0.200
C4		0.203Typ.	
D		1.050Typ.	
D1	0.400	0.500	0.600
R1		0.200Typ.	
R2		0.200Typ.	
Θ1		17°Typ.	
Θ2		13°Typ.	
Θ3		0°~ 8°Typ.	
Θ4		4°~ 12°Typ.	

## Order Information

Product	Marking	Package	Packaging	Min Unit Quantity
VS3009DS	VS3009DS	SOP8	3000/Reel	6000

## Customer Service

### Sales and Service:

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